

ON Semiconductor **10/16/2019**

Base Part			Pb-free
Orderable Part		MC78L05ACPXA	Total weight (mg) 218.2833
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #
Die	0.075	Silicon (Si)	7440-21-3
Die Attach	0.0375	Silver (Ag)	7440-22-4
		Phenolic Resin-2	54208-63-8
Lead Frame	100.2884	Manganese (Mn)	7439-96-5
		Nickel (Ni)	7440-02-0
		Iron (Fe)	7439-89-6
		Copper (Cu)	7440-50-8
Mold Compound-Black	112	2,6-dibromo-4-[1-(3-bromo-4-hydroxyphenyl)-1-methylethyl]phenol	6386-73-8
		Ortho Cresol Novolac Resin	29690-82-2
		Antimony Trioxide (Sb2O3)	1309-64-4
		Carbon Black (C)	1333-86-4
		Silica (SiO2)	14464-46-1
Plating	5.85	Tin (Sn)	7440-31-5
Wire Bond - Cu	0.0324	Copper (Cu)	7440-50-8

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels of dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:

<http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF>